

# NSR01L30MX

## Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current.

### Features

- Very Low Forward Voltage Drop – 350 mV @ 1 mA
- Low Reverse Current – 0.2  $\mu$ A @ 10 V
- 100 mA of Continuous Forward Current
- ESD Rating – Human Body Model: Class 3B  
– Machine Model: Class C
- This is a Halide-Free Device
- This is a Pb-Free Device

### Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

### Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

### MAXIMUM RATINGS

| Rating  | Symbol    | Value        | Unit    |
|---|-----------|--------------|---------|
| Reverse Voltage                               | $V_R$     | 30           | V       |
| Forward Current (DC)                          | $I_F$     | 100          | mA      |
| Forward Surge Current<br>(60 Hz @ 1 cycle)    | $I_{FSM}$ | 2.0          | A       |
| ESD Rating: Human Body Model<br>Machine Model | ESD       | >8.0<br>>400 | kV<br>V |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



**ON Semiconductor®**

[www.onsemi.com](http://www.onsemi.com)

## 30 V SCHOTTKY BARRIER DIODE



X3DFN2  
CASE 152AF

### MARKING DIAGRAM



L = Specific Device Code  
(Rotated 180°)  
M = Date Code

### ORDERING INFORMATION

| Device        | Package             | Shipping†              |
|---------------|---------------------|------------------------|
| NSR01L30MXT5G | X3DFN2<br>(Pb-Free) | 10000 /<br>Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NSR01L30MX

## THERMAL CHARACTERISTICS

| Characteristic   | Symbol                   | Min | Typ | Max         | Unit                                     |
|--|--------------------------|-----|-----|-------------|--|
| Thermal Resistance<br>Junction-to-Ambient (Note 1)<br>Total Power Dissipation @ $T_A = 25^\circ\text{C}$ | $R_{\theta JA}$<br>$P_D$ |     |     | 695<br>180  | $^\circ\text{C}/\text{W}$<br>$\text{mW}$ |
| Storage Temperature Range  | $T_{stg}$                |     |     | -55 to +150 | $^\circ\text{C}$                         |
| Junction Temperature   | $T_J$                    |     |     | +150        | $^\circ\text{C}$                         |

1. Mounted onto a 4 in square FR-4 board 100 mm sq. 2 oz. Cu 0.06" thick single-sided. Operating to steady state.

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic   | Symbol | Min | Typ | Max          | Unit          |
|--|--------|-----|-----|--------------|---------------|
| Reverse Leakage<br>( $V_R = 10\text{ V}$ )<br>( $V_R = 30\text{ V}$ )  | $I_R$  |     |     | 0.2<br>0.5   | $\mu\text{A}$ |
| Forward Voltage<br>( $I_F = 1\text{ mA}$ )<br>( $I_F = 10\text{ mA}$ ) | $V_F$  |     |     | 0.35<br>0.46 | V             |
| Total Capacitance<br>( $V_R = 5.0\text{ V}$ , $f = 1\text{ MHz}$ )     | CT     |     | 0.8 |              | pF            |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# NSR01L30MX

## TYPICAL CHARACTERISTICS

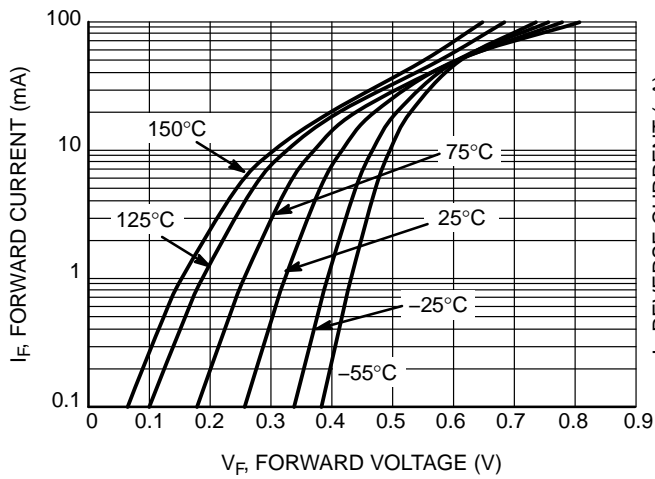


Figure 1. Forward Voltage

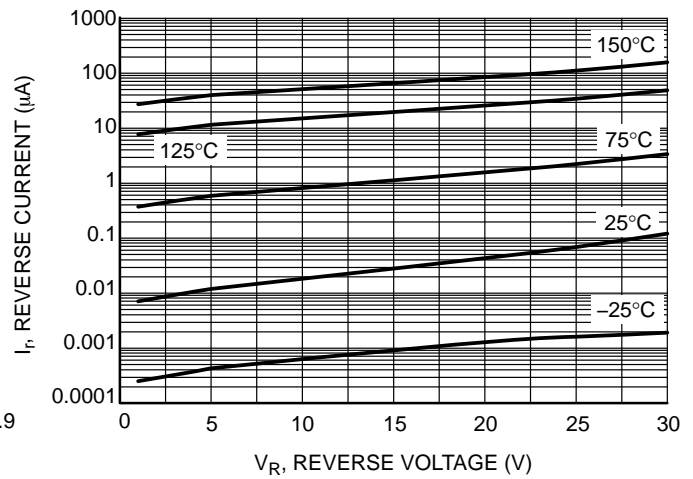


Figure 2. Leakage Current

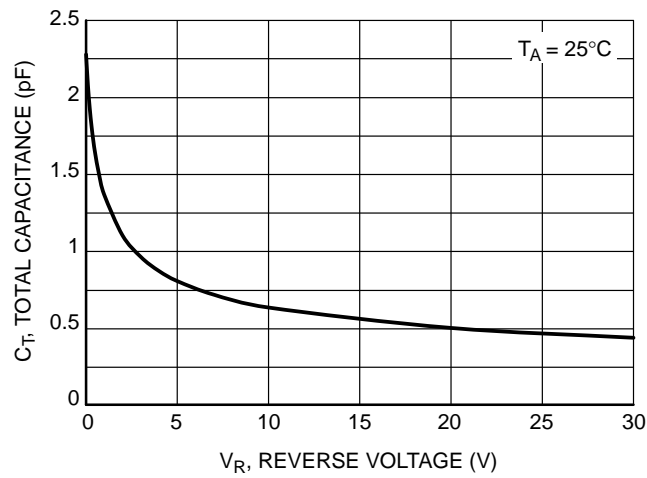
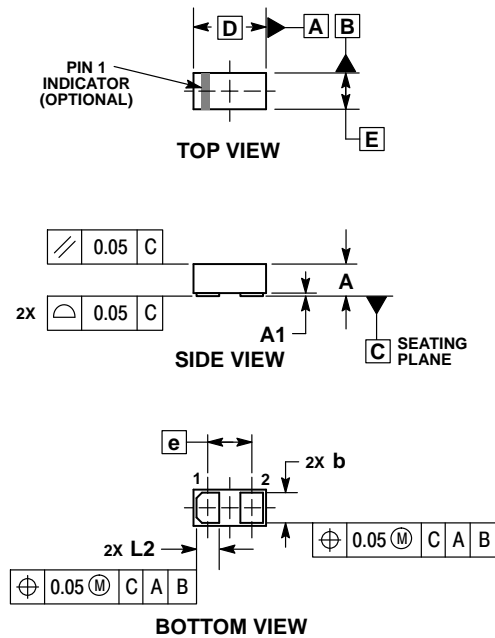


Figure 3. Total Capacitance

# NSR01L30MX

## PACKAGE DIMENSIONS

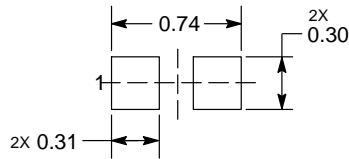
**X3DFN2, 0.62x0.32, 0.355P, (0201)**  
**CASE 152AF**  
**ISSUE A**



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

| MILLIMETERS |           |      |
|-------------|-----------|------|
| DIM         | MIN       | MAX  |
| A           | 0.25      | 0.33 |
| A1          | —         | 0.05 |
| b           | 0.22      | 0.28 |
| D           | 0.58      | 0.66 |
| E           | 0.28      | 0.36 |
| e           | 0.355 BSC |      |
| L2          | 0.17      | 0.23 |

### RECOMMENDED MOUNTING FOOTPRINT\*



See Application Note AND8398/D for more mounting details  
 \*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### PUBLICATION ORDERING INFORMATION

**LITERATURE FULFILLMENT:**  
 Literature Distribution Center for ON Semiconductor  
 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
 USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
 Phone: 421 33 790 2910  
**Japan Customer Focus Center**  
 Phone: 81-3-5817-1050

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)  
**Order Literature:** <http://www.onsemi.com/orderlit>  
 For additional information, please contact your local Sales Representative